

Materials Declaration

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Completed by Bruce Clark
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Product Family : DIP14 ECL Oscillator Type (FSL Series)

			Component	Content (mg)	Content (w t %)	(CAS Number)	
Cover	Osc Cover		Nickel (Ni)	0.303	0.01%	7440-02-0	
			Iron (Fe)	1081.80	27.46%	7439-89-6	
	Xtal Cover		Nickel (Ni)	44.70	1.135%	7440-02-0	
			Copper (Cu)	172.80	4.387%	7440-50-8	
			Phosphorus (P)	0.153	0.0039%	7723-14-0	
Base	Osc Base		Iron (Fe)	1860.400	47.2%	7439-89-6	
			Carbon C	1.100	0.03%	7440-44-0	
			Manganese (Mn)	5.400	0.14%	7439-96-5	
			Phosphorus (P)	0.400	0.010%	7723-14-0	
			Sulfur (S)	0.400	0.01%	7704-34-9	
			Nickel (Ni)	126.000	3.20%	7440-02-0	
			Silicon (Si)	0.400	0.010%	7440-21-3	
			Cobalt (Co)	33.200	0.84%	7440-48-4	
			Silver (Ag)	0.600	0.02%	7440-22-4	
			Copper (Cu)	0.100	0.003%	7440-50-8	
			Silicon Dioxide (SiO ₂)	39.200	0.995%	14808-60-7	
			Aluminum Oxide (Al ₂ O ₃)	4.600	0.117%	1344-28-1	
			Boron Oxide (B ₂ O ₃)	0.600	0.015%	1303-86-2	
			Barium Oxide (BaO)	6.600	0.168%	1304-28-5	
			Zinc Oxide (ZnO)	2.400	0.061%	1314-13-2	
		Sodium Oxide (Na ₂ O)	3.267	0.083%	1313-59-3		
		Potassium Oxide (K ₂ O)	3.267	0.083%	12136-45-7		
		Lithium Oxide (Li ₂ O)	3.267	0.083%	12057-24-8		
		Tin (Sn)	0.300	0.008%	7440-31-5		
		Lead (Pb)	0.200	0.005%	7439-92-1		
		Xtal Base	Base Body	Nickel (Ni)	30.400	0.77%	7440-02-0
				Iron (Fe)	56.600	1.44%	7439-89-6
				Cobalt (Co)	17.800	0.45%	7440-48-4
			Leads	Nickel (Ni)	9.530	0.24%	7440-02-0
				Iron (Fe)	17.700	0.45%	7439-89-6
				Cobalt (Co)	5.590	0.14%	7440-48-4
			Blank Supporter	Nickel (Ni)	0.090	0.00%	7440-02-0
				Iron (Fe)	0.850	0.02%	7439-89-6
				Chromium (Cr)	0.210	0.01%	7440-47-3
			Glass Seals	Silicon Dioxide (SiO ₂)	3.120	0.079%	14808-60-7
				Aluminum Oxide (Al ₂ O ₃)	0.290	0.007%	1344-28-1
				Boron Oxide (B ₂ O ₃)	0.960	0.024%	1303-86-2
				Barium Oxide (BaO)	0.140	0.004%	1304-28-5
			Plating	Nickel (Ni)	3.280	0.08%	7440-02-0
				Phosphorus (P)	0.140	0.004%	7723-14-0
		Gold (Au)		0.200	0.005%	7440-57-5	
	H/IC	Inductor	Terminal	Lead (Pb)	0.020	0.000508%	7439-92-1
				Tin (Sn)	0.117	0.002970%	7440-31-5
				Nickel (Ni)	0.063	0.001599%	7440-02-0
			Conductor	Silver (Ag)	0.690	0.017516%	7440-22-4
			Ceramic	Silicon (Si)	1.270	0.032240%	7440-21-3
				Magnesium (Mg)	0.342	0.008682%	7439-95-4
				Aluminum (Al)	0.074	0.001879%	7429-90-5
				Sulfur (S)	0.429	0.010890%	7704-34-9
				Cobalt (Co)	0.00063	0.000016%	7440-48-4
		Reflow Solder		Tin (Sn)	19.400	0.492481%	7440-31-5
			Silver (Ag)	0.603	0.015308%	7440-22-4	

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FSL Materials Continued

H/IC contd	Chip Cap		Copper (Cu)	0.100	0.002539%	7440-50-8	
			Tin (Sn)	0.095	0.0024116%	7440-31-5	
			Nickel (Ni)	0.095	0.0024116%	7440-02-0	
			Silver (Ag)	0.912	0.0231517%	7440-22-4	
			Titanium Oxide (TiO ₂)	8.310	0.2109545%	13463-67-7	
			Palladium (Pd)	2.510	0.0637179%	7440-05-3	
	Substrate		Epoxy Resin	218.000	5.534066%		
			Copper (Cu)	32.700	0.830110%	7440-50-8	
			Acrylic Resist Ink	4.470	0.001134737		
	Resistor	Alumina Substrate		Aluminum Oxide (Al ₂ O ₃)	9.73	0.247002%	1344-28-1
				Silicon Dioxide (SiO ₂)	0.301	0.007641%	14808-60-7
		Electrode Paste		Silver (Ag)	0.211	0.005356%	7440-22-4
				Palladium (Pd)	0.0162	0.000411%	7440-50-3
				Lead Oxide (PbO)	0.0243	0.000617%	1317-36-8
				Silicon Dioxide (SiO ₂)	0.0162	0.000411%	7631-86-9
				Boron Oxide (B ₂ O ₃)	0.00135	0.000034%	1303-86-2
				Titanium Oxide (TiO ₂)	0.00135	0.000034%	13463-67-7
		Resistor Paste		Ruthenium Oxide (RuO ₂)	0.0484	0.001229%	12036-10-1
				Lead Oxide (PbO)	0.0946	0.002401%	1317-36-8
				Silicon Dioxide (SiO ₂)	0.0506	0.001285%	7631-86-9
				Boron Oxide (B ₂ O ₃)	0.0198	0.000503%	1303-86-2
				Aluminum Oxide (Al ₂ O ₃)	0.0044	0.000112%	1344-28-1
		Protection Glass		Lead Oxide (PbO)	0.121	0.003072%	1317-36-8
				Silicon Dioxide (SiO ₂)	0.066	0.001675%	7631-86-9
				Boron Oxide (B ₂ O ₃)	0.0242	0.000614%	1303-86-2
				Aluminum Oxide (Al ₂ O ₃)	0.0088	0.000223%	1344-28-1
		Plating		Nickel (Ni)	0.219	0.005559%	7440-02-0
				Tin (Sn)	0.219	0.005559%	7440-31-5
		Mold IC		Aluminum (Al)	0.0016	0.00004%	7429-90-5
				Molybdenum (Mo)	0.0003	0.000008%	7439-98-7
				Silicon (Si)	0.992	0.03%	7440-21-3
				Gold (Au)	0.200	0.005%	7440-57-5
				Silver (Ag)	1.310	0.033255%	7440-22-4
			Nickel (Ni)	8.400	0.213239%	7440-02-0	
			Iron (Fe)	11.600	0.294473%	7439-89-6	
			Silica	46.600	1.182970%		
			Phenol Resin	4.660	0.118297%		
			Tin (Sn)	0.531	0.013480%	7440-31-5	
			Lead (Pb)	0.060	0.001523%	7439-92-1	
			Antimony Oxide (Sb ₂ O ₃)	2.000	0.050771%	1309-64-4	
			Aromatic Hydrocarbon	2.660	0.067526%		
			Epoxy Resin	9.980	0.253349%		
			Other	6.398	0.162417%		
	Crystal		Crystal		Silicon Dioxide (SiO ₂)	4.090	0.10%
		Electrode		Silver (Ag)	0.019	0.0005%	7440-22-4
				Nickel (Ni)	0.000159	0.000004%	7440-02-0
		Adhesive		Silver (Ag)	0.00037	0.000009%	7440-22-4
			Silicon (Si)	0.000125	0.000003%	7440-21-3	
TOTAL				3939.2	100.00%		